

PANDUIT® STRUCTUREDGROUND™ Access Floor Grounding Clamp



specifications

The underfloor mesh common bonding network (MCBN) shall be designed to provide a high performance electrical bond to the grounding network by minimizing the overall resistance. The MCBN shall be constructed of a minimum of #6 AWG bare copper class B conductors. The conductors shall be installed in a grid pattern. At each conductor intersection, the conductors shall be in direct contact with one another and be bonded to each other by a single grounding clamp. The grounding clamp shall create a bond to the access floor by bonding the pedestals to the MCBN conductors. MCBN grid shall be on four foot (120cm) centers allowing for bonding of one pedestal from each access floor tile. All metallic elements shall be bonded to the MCBN, including rack/cabinet jumpers, underfloor wire basket, water pipes and HVAC units. The access floor grounding clamp shall be TIA-942 compliant, listed for its purpose with a nationally recognized testing laboratory, capable of withstanding fault currents and RoHS compliant. Clamp shall be constructed of materials to eliminate zinc whiskers.



technical information

Performance level:	TIA-942 Compliant, UL 467 Listed, CSA Certified, RoHS Compliant
	Mounts to 3/4" (19.1mm) and 1" (25.4mm) round and square pedestals
	Bonds a single or two perpendicular MCBN conductors from conductor sizes #6 – 1/0 AWG (16 – 50mm ²)
Dimensions:	GPQC1/0: 3.50"H x 1.75"W x 3.50"L (88.9mm x 44.5mm x 88.9mm)

key features and benefits

Quad bolt design	Securely holds conductor in place while other conductor is being installed for a faster installation; minimizes MCBN resistance to create a high performance bond
Wide wire range-taking capability	Accommodates conductors from #6 – 1/0 AWG which minimizes inventory requirements
Captive U-bolt design	Bonds to both 3/4" and 1" round and square pedestals with a single hinged bolt to speed installation
Stainless steel hardware	Eliminates zinc whiskers to increase equipment reliability

applications

PANDUIT® STRUCTUREDGROUND™ Access Floor Grounding Clamp includes innovative design features to install MCBNs faster than with other manufacturers' clamps. This superior solution provides a visually verifiable, high quality bond between the

MCBN conductors and access floor to protect network equipment and personnel, maintain system performance, and maximize uptime. The access floor grounding clamp is part of the comprehensive STRUCTUREDGROUND™ Grounding System solution.

For the complete STRUCTUREDGROUND™ Grounding System offering, refer to www.panduit.com/dcgrounding

www.panduit.com

Access Floor Grounding Clamp



#6 – 1/0 AWG
(16 – 50mm²),
3.50" (88.9mm) H x
1.75" (44.5mm) W x
3.50" (88.9mm) L: GPQC1/0

Related Products

Copper Compression HTAPs and Clear Covers



#2 – #6 AWG
(25 – 16mm²) run,
#2 – #6 AWG
(25 – 16mm²) tap: HTWC2-2-1
250 kcmil – #2 AWG
(120 – 35mm²) run,
#2 – #6 AWG
(25 – 16mm²) tap: HTWC250-2-1

Bronze, U-Bolt Grounding Clamps



1/2" or 3/4"
(20mm or 25mm)
iron pipe size,
#8 AWG SOL –
#4 AWG STR
(10mm² SOL –
16mm² STR): GPL-8-Q
1" (32mm)
iron pipe size,
#4 AWG SOL –
2/0 AWG STR
(16 – 70mm² STR): GPL-15-X

Code Conductor, Thin Wall, CTAPs



#6 AWG
(16mm²) run,
#6 AWG
(16mm²) tap: CTAPF4-12-C
#2 AWG
(35mm²) run,
#2 AWG
(35mm²) tap: CTAPF1/0-12-L
1/0 AWG
(50mm²) run,
1/0 AWG
(50mm²) tap: CTAPF3/0-12-Q

Split Bolt, Copper



#6 AWG (16mm²)
to wire basket: SBC3-C

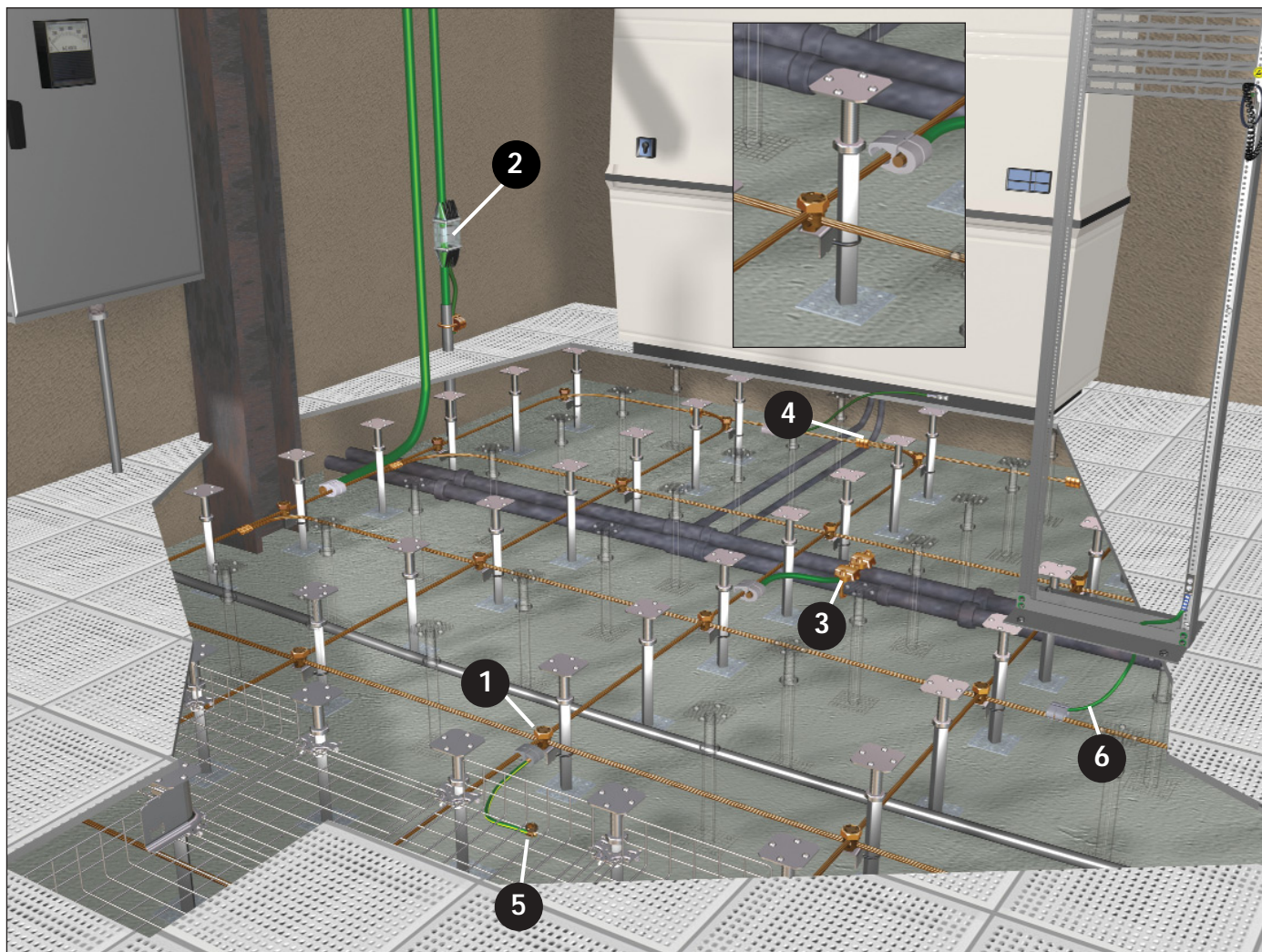
Common Bonding Network (CBN) Jumper Kit (factory terminated on one end)



60" (1.52m) L,
#6 AWG (16mm²),
#6 – #2 AWG
(16 – 25mm²) HTAP: RGCBNJ660P22
60" (1.52m) L,
#6 AWG (16mm²),
#2 AWG – 250 kcmil
(35 – 120mm²) HTAP: RGCBNJ660PY

PANDUIT® STRUCTUREDGROUND™ Access Floor Grounding Clamp

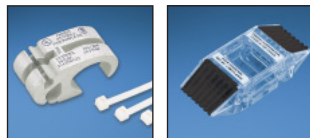
Access Floor MCBN Roadmap



1 Access Floor Grounding Clamp: GPQC



2 Copper Compression HTAP and Clear Cover: HTWC



3 Bronze, U-Bolt Grounding Clamp: GPL



4 Code Conductor, Thin Wall, CTAP: CTAPF



5 Split Bolt, Copper: SBC



6 Common Bonding Network (CBN) Jumper Kit: RGCBNJ



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